



PROCOIL IndC (Inductive Coupling)

Reliable and cost-efficient solution

Linxens PROCOIL IndC is based on dual-interface cards providing a reliable, robust and proven solution for the smart card market.



Wire booster antenna and the module are connected to each other by inductive coupling. The absence of any mechanical interconnection between module and antenna makes it one of the most robust dual-interface solutions available on the market today. This proven technology simplifies card production and improves yield rates.

Wire booster antenna leverages the advantages of wire-embedding and inductive coupling technologies. The ID2/3 antenna design meets the EMV requirements and allows card embossing without any restriction.


The thin tracks of the wire antenna only occupy small area inside the card body. This provides room for creativity in case of translucent cards, however also prevents "ghost images" on the card surface when applying sophisticated graphics.

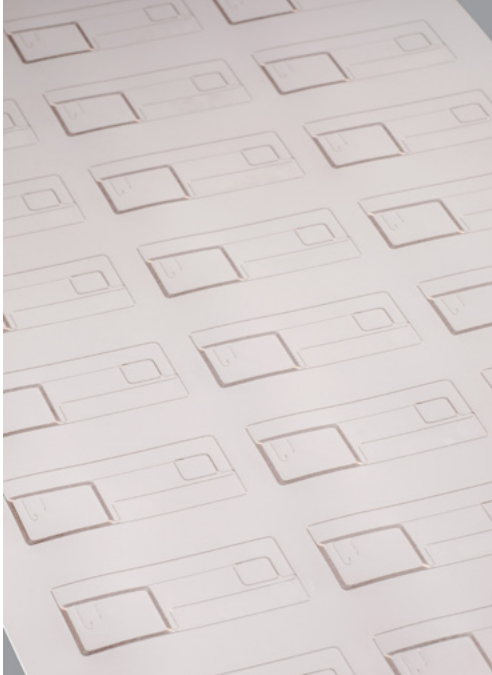
PROCOIL IndC wire booster antenna is delivered in customized sheet formats between 170µm and 420µm, and is suitable for manual as well as fully automated collation. All available PROCOIL IndC substrates are suitable for hot lamination, which enables the creation of a durable, mono-material card structure. Compared to card structures involving adhesives, such a monolithic construction significantly reduces the risk of card body delamination.

Manufacturing a card with inductive coupling technology requires no equipment investment beyond what is needed to manufacture a conventional contact-chip card. Therefore it represents one of today's most economical ways to produce dual-interface cards.

Product	Antenna Size	Dimensions	Thickness	Available IC
	ID 2/3	Sheet layout according to customer requirements	170 µm to 420 µm	Infineon SLE77/ SLE78 chip family with Infineon module S-COM8.6
	ID 2/3	Sheet layout according to customer requirements	170 µm to 420 µm	Infineon SLE77/ SLE78 chip family with Infineon module S-COM8.4

Additional product configurations are available upon request.
Note: Pictures are for illustration only and are not to scale.

 **RFID**



Overview

Operating Frequency

- 13.56 MHz

Material

- PVC
- Other substrates upon request

International Standards

- ISO 14443

Application Area

Dual Interface Cards for:

- Contactless payment

Benefits

- Customized sheet formats available
- Full hot lamination capabilities
- Economic integration into existing card manufacturing process